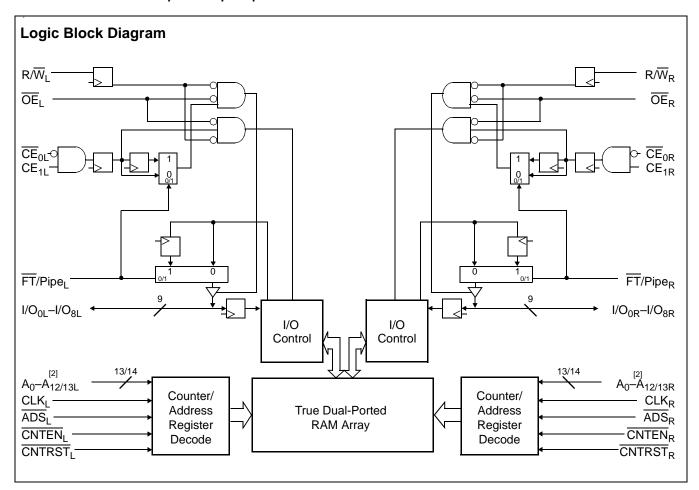


8K/16K x 9 Synchronous Dual-Port Static RAM

Features

- True dual-ported memory cells which allow simultaneous access of the same memory location
- Two Flow-Through/Pipelined devices
 - -8K x 9 organization (CY7C09159A)
 - -16K x 9 organization (CY7C09169A)
- Three Modes
 - Flow-Through
 - Pipelined
 - -Burst
- · Pipelined output mode on both ports allows fast 100-MHz cycle time
- 0.35-micron CMOS for optimum speed/power

- High-speed clock to data access 6.5^[1]/7.5/9/12 ns (max.)
- · Low operating power
 - Active = 200 mA (typical)
 - Standby = 0.05 mA (typical)
- Fully synchronous interface for easier operation
- · Burst counters increment addresses internally
 - -Shorten cycle times
 - Minimize bus noise
 - Supported in Flow-Through and Pipelined modes
- Dual Chip Enables for easy depth expansion
- Automatic power-down
- Commercial and Industrial temperature ranges
- Available in 100-pin TQFP



- 1. See page 6 for Load Conditions. 2. A_0 – A_{12} for 8K; A_0 – A_{13} for 16K.



Functional Description

The CY7C09159A and CY7C09169A are high-speed synchronous CMOS 8K and 16K x 9 dual-port static RAMs. Two ports are provided, permitting independent, simultaneous access for reads and writes to any location in memory [3]. Registers on control, address, and data lines allow for minimal set-up and hold times. In pipelined output mode, data is registered for decreased cycle time. Clock to data valid $t_{\rm CD2} = 6.5~{\rm ns}^{[1]}$ (pipelined). Flow-through mode can also be used to bypass the pipelined output register to eliminate access latency. In flow-through mode data will be available $t_{\rm CD1} = 15~{\rm ns}$ after the address is clocked into the device. Pipelined output or flow-through mode is selected via the $\overline{\rm FT}/{\rm Pipe}$ pin.

Each port contains a burst counter on the input address register. The internal write pulse width is independent of the LOW-to-HIGH transition of the clock signal. The internal write pulse is self-timed to allow the shortest possible cycle times.

A HIGH on $\overline{\text{CE}}_0$ or LOW on CE_1 for one clock cycle will power down the internal circuitry to reduce the static power consumption. The use of multiple Chip Enables allows easier banking of multiple chips for depth expansion configurations. In the pipelined mode, one cycle is required with $\overline{\text{CE}}_0$ LOW and CE_1 HIGH to reactivate the outputs.

Counter enable inputs are provided to stall the operation of the address input and utilize the internal address generated by the internal counter for fast interleaved memory applications. A port's burst counter is loaded with the port's Address Strobe (ADS). When the port's Count Enable (CNTEN) is asserted, the address counter will increment on each LOW-to-HIGH transition of that port's clock signal. This will read/write one word from/into each successive address location until CNTEN is deasserted. The counter can address the entire memory array and will loop back to the start. Counter Reset (CNTRST) is used to reset the burst counter.

All parts are available in 100-pin Thin Quad Plastic Flatpack (TQFP) packages.

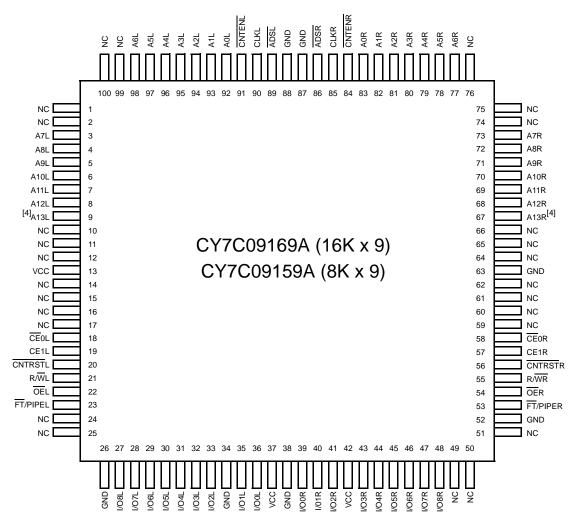
Note:

3. When simultaneously writing to the same location, final value cannot be guaranteed.



Pin Configuration





Note:

4. This pin is NC for CY7C09159A.



Selection Guide

	CY7C09159A CY7C09169A -6 ^[1]	CY7C09159A CY7C09169A -7	CY7C09159A CY7C09169A -9	CY7C09159A CY7C09169A -12
f _{MAX2} (MHz) (Pipelined)	100	83	67	50
Max. Access Time (ns) (Clock to Data, Pipelined)	6.5	7.5	9	12
Typical Operating Current I _{CC} (mA)	250	235	215	195
Typical Standby Current for I _{SB1} (mA) (Both Ports TTL Level)	45	40	35	30
Typical Standby Current for I _{SB3} (mA) (Both Ports CMOS Level)	0.05	0.05	0.05	0.05

Pin Definitions

Left Port	Right Port	Description
A _{0L} -A _{13L}	A _{0R} -A _{13R}	Address Inputs (A ₀ -A ₁₂ for 8K; A ₀ -A ₁₃ for 16K devices).
ADS _L	ADS _R	Address Strobe Input. Used as an address qualifier. This signal should be asserted LOW during normal read or write transactions. Asserting this signal LOW also loads the burst address counter with data present on the I/O pins.
CE _{0L} ,CE _{1L}	CE _{0R} ,CE _{1R}	Chip Enable Input. To select either the left or right port, both \overline{CE}_0 AND CE_1 must be asserted to their active states ($\overline{CE}_0 \le V_{IL}$ and $CE_1 \ge V_{IH}$).
CLK _L	CLK _R	Clock Signal. This input can be free running or strobed. Maximum clock input rate is f _{MAX} .
CNTENL	CNTEN _R	Counter Enable Input. Asserting this signal <u>LOW increments</u> the <u>burst</u> address counter of its respective port on each rising edge of CLK. CNTEN is disabled if ADS or CNTRST are asserted LOW.
CNTRST	CNTRST _R	Counter Reset Input. Asserting this signal LOW resets the burst address counter of its respective port to zero. CNTRST is not disabled by asserting ADS or CNTEN.
I/O _{0L} –I/O _{8L}	I/O _{0R} –I/O _{8R}	Data Bus Input/Output (I/O ₀ -I/O ₇ for x8 devices; I/O ₀ -I/O ₈ for x9 devices).
OEL	OE _R	Output Enable Input. This signal must be asserted LOW to enable the I/O data pins during read operations.
R/\overline{W}_L	R/W _R	Read/Write Enable Input. This signal is asserted LOW to write to the dual port memory array. For read operations, assert this pin HIGH.
FT/PIPE _L	FT/PIPE _R	Flow-Through/Pipelined Select Input. For flow-through mode operation, assert this pin LOW. For pipelined mode operation, assert this pin HIGH.
GND	-	Ground Input.
NC		No Connect.
V _{CC}		Power Input.

Maximum Ratings^[5]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Note:

5. The Voltage on any input or I/O pin cannot exceed the power pin during power-up

Outpu	ut Current into Outputs (LOW)	20 mA
Static	Discharge Voltage	>2001V
Latch-	-Up Current	>200 mA

Operating Range

Range	Ambient Temperature	v _{cc}
Commercial	0°C to +70°C	5V ± 10%
Industrial ^[6]	-40°C to +85°C	5V ± 10%

6. Industrial Parts are available in CY7C09169A only.



Electrical Characteristics Over the Operating Range

				CY7C09159A CY7C09169A											
				-6 ^[1]			-7			-9			-12		
Parameter	Description		Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
V _{OH}	Output HIGH Voltage (V _{CC} = Min., I _{OH} = -4.0) mA)	2.4			2.4			2.4			2.4			V
V _{OL}	Output LOW Voltage (V _{CC} = Min., I _{OH} = +4.0) mA)			0.4			0.4			0.4			0.4	V
V_{IH}	Input HIGH Voltage		2.2			2.2			2.2			2.2			V
V _{IL}	Input LOW Voltage				0.8			0.8			0.8			0.8	V
I _{OZ}	Output Leakage Curre	nt	-10		10	-10		10	-10		10	-10		10	μΑ
I _{CC}	Operating Current	Com'l.		250	450		235	420		210	350		200	305	mA
	(V _{CC} = Max., I _{OUT} = 0 mA) Outputs Disabled	Ind. ^[6]								245	410				mA
I _{SB1}	Standby Current (Both	Com'l.		45	115		40	105	1	35	95		30	85	mA
	$\frac{\text{Ports TTL}}{\text{CE}_{L} \& \text{CE}_{R}} \ge V_{\text{IH}},$ $f = f_{\text{MAX}}$	Ind. ^[6]								50	110				mA
I _{SB2}	Standby Current (One	Com'l.		175	235		160	220		145	205		125	190	mA
	$\frac{\text{Port TTL Level}}{\text{CE_L} \mid \text{CE_R} \ge \text{V}_{\text{IH}}},$ $f = f_{\text{MAX}}$	Ind. ^[6]								160	220				mA
I _{SB3}	Standby Current (Both	Com'l.		0.05	0.5		0.05	0.5	Ī	0.05	0.5		0.05	0.5	mA
	$\frac{\text{Ports CMOS Level})^{[7]}}{\text{CE}_{L} \& \text{CE}_{R} \ge}$ $V_{CC} - 0.2V, f = 0$	Ind. ^[6]								0.05	0.5				mA
I _{SB4}	Standby Current (One	Com'l.		160	200		145	185	1	130	170		110	150	mA
	$\frac{\text{Port CMOS Level}}{\text{CE}_{L} \mid \text{CE}_{R} \ge \text{V}_{IH}},$ $f = f_{MAX}$	Ind. ^[6]			1			1		145	185			ı	mA

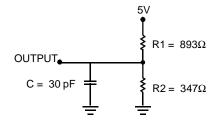
Capacitance

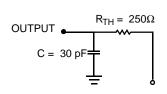
Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	10	pF
C _{OUT}	Output Capacitance	$V_{CC} = 5.0V$	10	pF

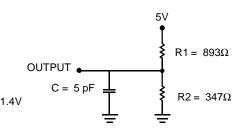
Note:
7. \overline{CE}_L and \overline{CE}_R are internal signals. To select either the left or right port, both \overline{CE}_0 AND CE_1 must be asserted to their active states $(\overline{CE}_0 \le V_{IL})$ and $CE_1 \ge V_{IH}$.



AC Test Loads





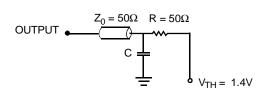


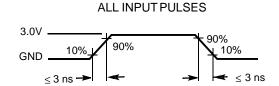
(a) Normal Load (Load 1)

(b) Thévenin Equivalent (Load 1)

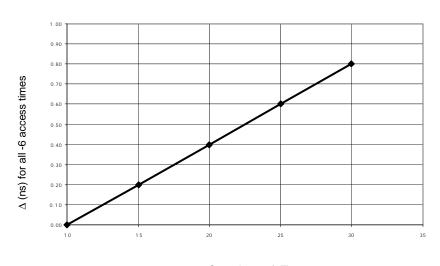
(c) Three-State Delay (Load 2) (Used for t_{CKLZ}, t_{OLZ}, & t_{OHZ} including scope and jig)

AC Test Loads (Applicable to -6 only)[8]





(a) Load 1 (-6 only)



Capacitance (pF)

(b) Load Derating Curve

Note:

8. Test Conditions: C = 10 pF.



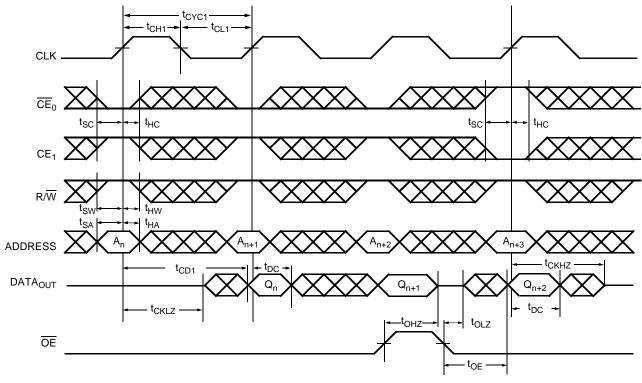
Switching Characteristics Over the Operating Range

					CY7CO)9159A)9169A				
		-6	[1]	-	7	-	9		12	
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
f _{MAX1}	f _{Max} Flow-Through		53		45		40		33	MHz
f _{MAX2}	f _{Max} Pipelined		100		83		67		50	MHz
t _{CYC1}	Clock Cycle Time - Flow-Through	19		22		25		30		ns
t _{CYC2}	Clock Cycle Time - Pipelined	10		12		15		20		ns
t _{CH1}	Clock HIGH Time - Flow-Through	6.5		7.5		12		12		ns
t _{CL1}	Clock LOW Time - Flow-Through	6.5		7.5		12		12		ns
t _{CH2}	Clock HIGH Time - Pipelined	4		5		6		8		ns
t _{CL2}	Clock LOW Time - Pipelined	4		5		6		8		ns
t _R	Clock Rise Time		3		3		3		3	ns
t _F	Clock Fall Time		3		3		3		3	ns
t _{SA}	Address Set-up Time	3.5		4		4		4		ns
t _{HA}	Address Hold Time	0		0		1		1		ns
t _{SC}	Chip Enable Set-up Time	3.5		4		4		4		ns
t _{HC}	Chip Enable Hold Time			0		1		1		ns
t _{SW}	R/W Set-up Time	3.5		4		4		4		ns
t _{HW}	R/W Hold Time	0		0		1		1		ns
t _{SD}	Input Data Set-up Time	3.5		4		4		4		ns
t _{HD}	Input Data Hold Time	0		0		1		1		ns
t _{SAD}	ADS Set-up Time	3.5		4		4		4		ns
t _{HAD}	ADS Hold Time	0		0		1		1		ns
t _{SCN}	CNTEN Set-up Time	3.5		4		4		4		ns
t _{HCN}	CNTEN Hold Time	0		0		1		1		ns
t _{SRST}	CNTRST Set-up Time	3.5		4		4		4		ns
t _{HRST}	CNTRST Hold Time	0		0		1		1		ns
t _{OE}	Output Enable to Data Valid		8		9		10		12	ns
t _{OLZ}	OE to Low Z	2		2		2		2		ns
t _{OHZ}	OE to High Z	1	7	1	7	1	7	1	7	ns
t _{CD1}	Clock to Data Valid - Flow-Through		15		18		20		25	ns
t _{CD2}	Clock to Data Valid - Pipelined		6.5		7.5		9		12	ns
t _{DC}	Data Output Hold After Clock HIGH			2		2		2		ns
t _{CKHZ}	Clock HIGH to Output High Z	2	9	2	9	2	9	2	9	ns
t _{CKLZ}	Clock HIGH to Output Low Z	2		2		2		2		ns
Port to Port	t Delays			•	1					ı
t _{CWDD}	Write Port Clock HIGH to Read Data Delay		30		35		40		40	ns
t _{CCS}	Clock to Clock Set-up Time		9		10		15		15	ns
	1	1	I	L				l .	1	i

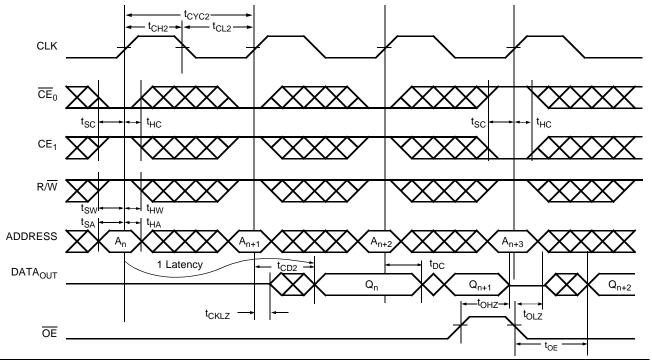


Switching Waveforms

Read Cycle for Flow-Through Output $(\overline{FT}/PIPE = V_{IL})^{[9, 10, 11, 12]}$



Read Cycle for Pipelined Operation (FT/PIPE = V_{IH})^[9, 10, 11, 12]



- 9. <u>OE</u> is asynchronously controlled; all other inputs are synchronous to the rising clock edge.

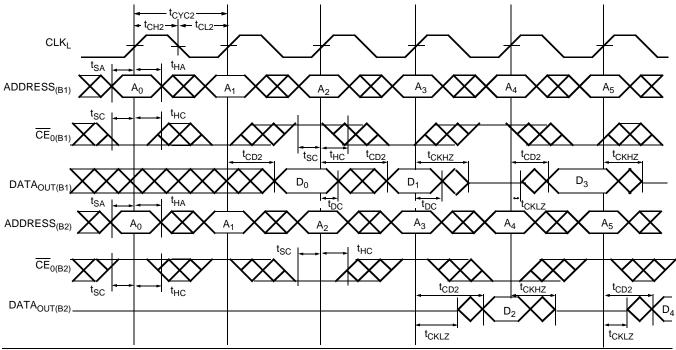
 10. ADS = V_{IL}, CNTEN and CNTRST = V_{IH}.

 11. The output is disabled (high-impedance state) by CE₀=V_{IL} or CE₁ = V_{IL} following the next rising edge of the clock.

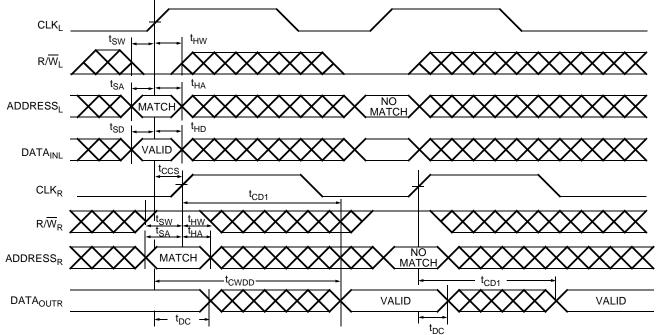
 12. Addresses do not have to be accessed sequentially since ADS = V_{IL} constantly loads the address on the rising edge of the CLK. Numbers are for reference only.



Bank Select Pipelined Read^[13, 14]



Left Port Write to Flow-Through Right Port Read^[15, 16, 17, 18]



- Notes:

 13. In this depth expansion example, B1 represents Bank #1 and B2 is Bank #2. Each Bank consists of one Cypress dual-port device from this data sheet.
 ADDRESS(B1) = ADDRESS(B2).

 14. OE and ADS = V_{IL}; CE_{1(B1)}, CE_{1(B2)}, R/W, CNTEN, and CNTRST = V_{IH}.

 15. The same waveforms apply for a right port write to flow-through left port read.

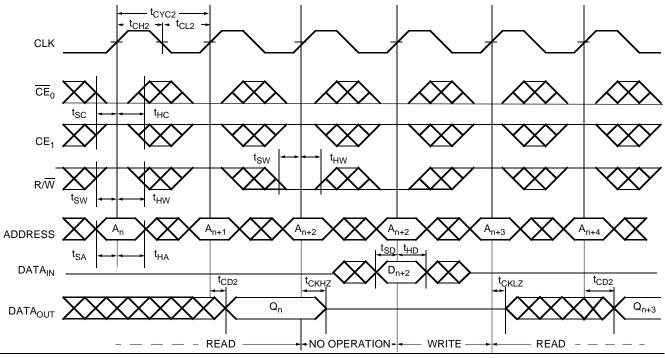
 16. CE₀ and ADS = V_{IL}; CE₁, CNTEN, and CNTRST = V_{IH}.

 17. OE = V_{IL} for the right port, which is being read from. OE = V_{IH} for the left port, which is being written to.

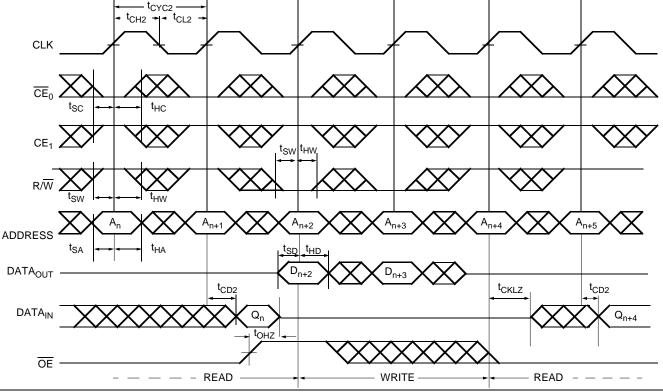
 18. It t_{CCS} ≤ maximum specified, then data from right port READ is not valid until the maximum specified for t_{CWDD}. If t_{CCS}>maximum specified, then data is not valid until tess + tess. toward does not apply in this case. valid until $t_{CCS} + t_{CD1}$. t_{CWDD} does not apply in this case.



Pipelined Read-to-Write-to-Read ($\overline{OE} = V_{IL}$)[12, 16, 19, 20]



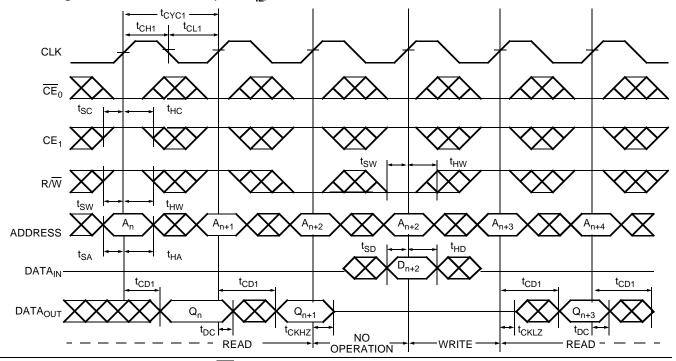
Pipelined Read-to-Write-to-Read (OE Controlled)^[12, 16, 19, 20]



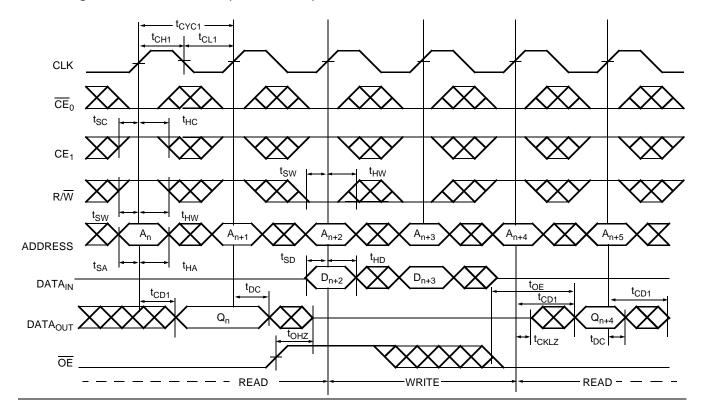
- Output state (HIGH, LOW, or High-Impedance) is determined by the previous cycle control signals.
 During "No operation," data in memory at the selected address may be corrupted and should be rewritten to ensure data integrity.



Flow-Through Read-to-Write-to-Read $(\overline{OE} = V_{IL})^{[10, 12, 16, 19]}$

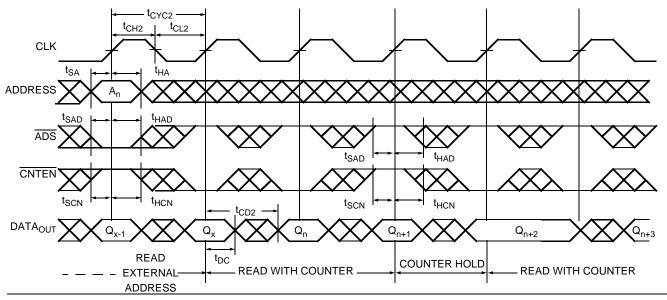


Flow-Through Read-to-Write-to-Read (OE Controlled)^[10, 12, 16, 19]

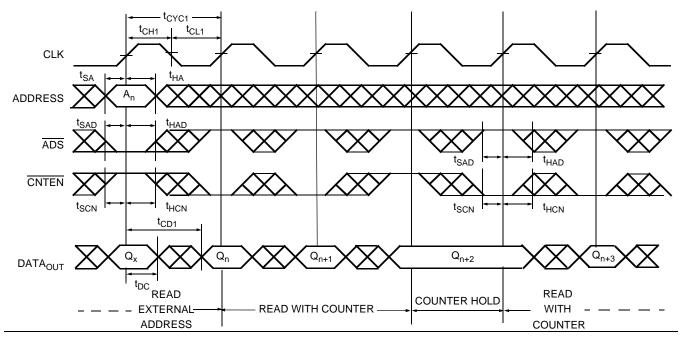




Pipelined Read with Address Counter Advance^[21]



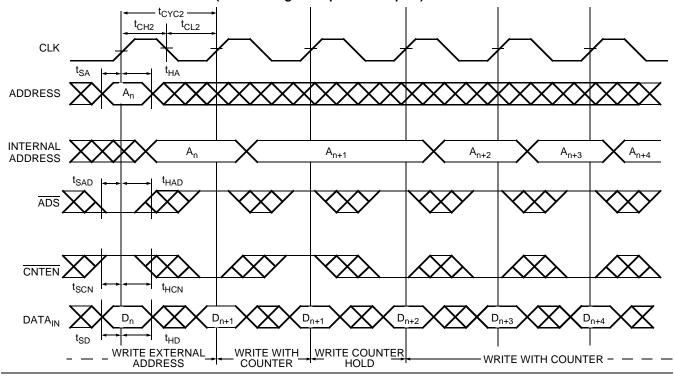
Flow-Through Read with Address Counter Advance^[21]



Note: 21. $\overline{CE_0}$ and \overline{OE} = V_{IL} ; CE_1 , R/\overline{W} and \overline{CNTRST} = V_{IH} .



Write with Address Counter Advance (Flow-Through or Pipelined Outputs) $\cite{[22,23]}$

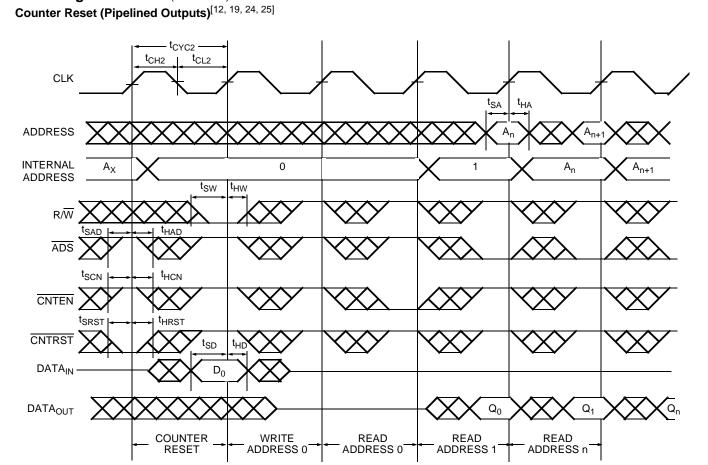


Notes:

22. \overline{CE}_0 and $R/\overline{W} = V_{IL}$; CE_1 and $\overline{CNTRST} = V_{IH}$.

23. The "Internal Address" is equal to the "External Address" when $\overline{ADS} = V_{IL}$ and equals the counter output when $\overline{ADS} = V_{IH}$.





Notes:

24. CE₀ = V_{IL}; CE₁ = V_{IH}.
 25. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset.



Read/Write and Enable Operation^[26, 27, 28]

		Inputs			Outputs	
OE	CLK	CE ₀	CE ₁	R/W	I/O ₀ –I/O ₈	Operation
Х	4	Н	Х	Х	High-Z	Deselected ^[29]
Х	4	Х	L	Х	High-Z	Deselected ^[29]
Х	4	L	Н	┙	D _{IN}	Write
L	4	L	Н	Н	D _{OUT}	Read ^[29]
Н	Х	L	Н	Х	High-Z	Outputs Disabled

Address Counter Control Operation^[26, 30, 31, 32]

Address	Previous Address	CLK	ADS	CNTEN	CNTRST	I/O	Mode	Operation
Х	Х	7	Х	Х	L	D _{out(0)}	Reset	Counter Reset to Address 0
A _n	Х	7	L	Х	Н	D _{out(n)}	Load	Address Load into Counter
Х	A _n	۲	Н	Н	Н	D _{out(n)}	Hold	External Address Blocked—Counter Disabled
Х	A _n	4	Н	L	Н	D _{out(n+1)}	Increment	Counter Enabled—Internal Address Generation

- 26. "X" = "Don't Care," "H" = V_{IH}, "L" = V_{IL}.

 27. ADS, CNTEN, CNTRST = "Don't Care."

 28. OE is an asynchronous input signal.

 29. When CE changes state in the pipelined mode, deselection and read happen in the following clock cycle.

 30. CE₀ and OE = V_{IL}; C_{E1} and R/W = V_{IH}.

 31. Data shown for flow-through mode; pipelined mode output will be delayed by one cycle.

 32. Counter operation is independent of CE₀ and CE₁.



Ordering Information

8K x9 Synchronous Dual-Port SRAM

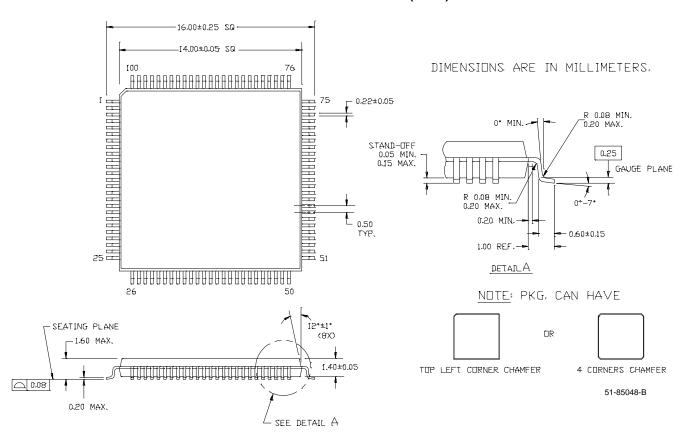
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
6.5 ^[1]	CY7C09159A-6AC	A100	100-Pin Thin Quad Flat Pack	Commercial
7.5	CY7C09159A-7AC	A100	100-Pin Thin Quad Flat Pack	Commercial
9	CY7C09159A-9AC	A100	100-Pin Thin Quad Flat Pack	Commercial
12	CY7C09159A-12AC	A100	100-Pin Thin Quad Flat Pack	Commercial

16K x9 Synchronous Dual-Port SRAM

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
6.5 ^[1]	CY7C09169A-6AC	A100	100-Pin Thin Quad Flat Pack	Commercial
7.5	CY7C09169A-7AC	A100	100-Pin Thin Quad Flat Pack	Commercial
9	CY7C09169A-9AC	A100	100-Pin Thin Quad Flat Pack	Commercial
	CY7C09169A-9AI	A100	100-Pin Thin Quad Flat Pack	Industrial
12	CY7C09169A-12AC	A100	100-Pin Thin Quad Flat Pack	Commercial

Package Diagram

100-Pin Thin Plastic Quad Flat Pack (TQFP) A100





Document Title: CY7C09159A/CY7C09169A 8K/16K x 9 Synchronous Dual-Port Static RAM Document Number: 38-06047						
REV. Issue Orig. of Change Description of Change						
**	110199	09/29/01	SZV	Change from Spec number: 38-00833 to 38-06047		
*A	122297	12/27/02	RBI	Power up requirements added to Maximum Ratings Information		